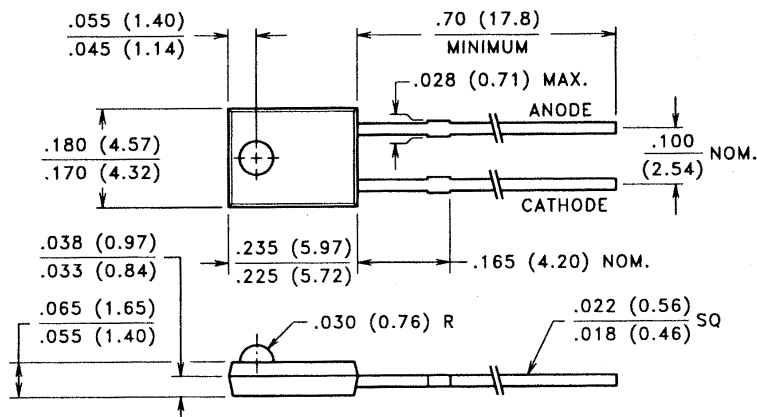


**PACKAGE DIMENSIONS** inch (mm)



**CASE 7 LATERAL**  
**CHIP SIZE: .011" x .011"**

**DESCRIPTION**

These side-looking packages are designed for use in PC board mounted interrupt detectors. The package is transfer molded plastic and contains a high efficiency, 880 nm, GaAlAs IRED die.

**RoHS Compliant**



**ABSOLUTE MAXIMUM RATINGS @ 25°C (unless otherwise noted) ■**

Maximum Temperatures			Maximum Reverse Voltage:	5.0V
Storage and Operating:	-40°C to 85°C		Maximum Reverse Current @ $V_R = 5V$ :	10 $\mu A$
Continuous Power Dissipation:	100 mW		Peak Wavelength (Typical):	880 nm
Derate above 30°C:	1.82 mW/°C		Junction Capacitance @ 0V, 1 MHz (Typ.):	14 pF
Maximum Continuous Current:	50 mA		Response Time @ $I_F = 20$ mA	
Derate above 30°C:	0.91 mA/°C		Rise: 1.0 $\mu s$ Fall: 1.0 $\mu s$	
Peak Forward Current, 10 $\mu s$ , 100 pps:	2.5 A		Lead Soldering Temperature:	260°C
Temp. Coefficient of Power Output (Typ.):	-8%/°C		(1.6 mm from case, 5 seconds max.)	

**ELECTRO-OPTICAL CHARACTERISTICS @ 25°C (See also GaAlAs curves, pages 108-110)**

Part Number ■	Output						Forward Drop		Half Power Beam Angle
	Irradiance				Radiant Intensity	Total Power	Test Current	$V_F$	
	$E_e$		Condition		$I_e$	$P_O$	$I_{FT}$	@ $I_{FT}$	
	mW/cm <sup>2</sup>		distance	Diameter	mW/sr	mW	mA	Volts	Typ.
	Min.	Typ.	mm	mm	Min.	Typ.	(Pulsed)	Typ. Max.	
VTE7172H	0.4	0.6	16.7	4.6	1.1	2.5	20	1.3 1.8	±25°
VTE7173H	0.6	0.8	16.7	4.6	1.7	5.0	20	1.3 1.8	±25°

■ Refer to General Product Notes, page 2.